FLIP CHIP MODULES
TEST SPECS

TYPE: M111

INVERTER

TEST	CONDITIONS	MINIMUM	MAXIMUM
V_{OUT} (0)	V_{CC} = +4.75V V_{IN} = +2.0 V I_{SINK} = +16 MA		+ 0.4 V
V_{OUT} (1)	V_{CC} = +4.75V V_{IN} = +0.8 V I_{LOAD} = -400 µA	+ 2.4 V	
I_{IN} (0)	V_{CC} = +5.25 V V_{IN} = +0.4 V		- 1.6 MA
I_{IN} (1)	V_{CC} = +5.25 V V_{IN} = +2.4 V		+ 40 µA
V_{TP} (PIN B2)	V_{CC} = +5.0 V MEASURE PIN B2 WITH INPUT RESISTANCE ≥ 1 MEG & ALL INPUTS GROUND	+2.82 V	+3.45 V
TD 1	V_{CC} = +5.0 V + 1.5V TO + 1.5V *		30 NSEC
TD 0	V_{CC} = +5.0 V + 1.5V TO + 1.5V *		15 NSEC

* RC LOAD - C = 150PF TO GND, R = 330Ω TO +4.75V

8/28/68

TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep the copper from lifting.
Oscilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.